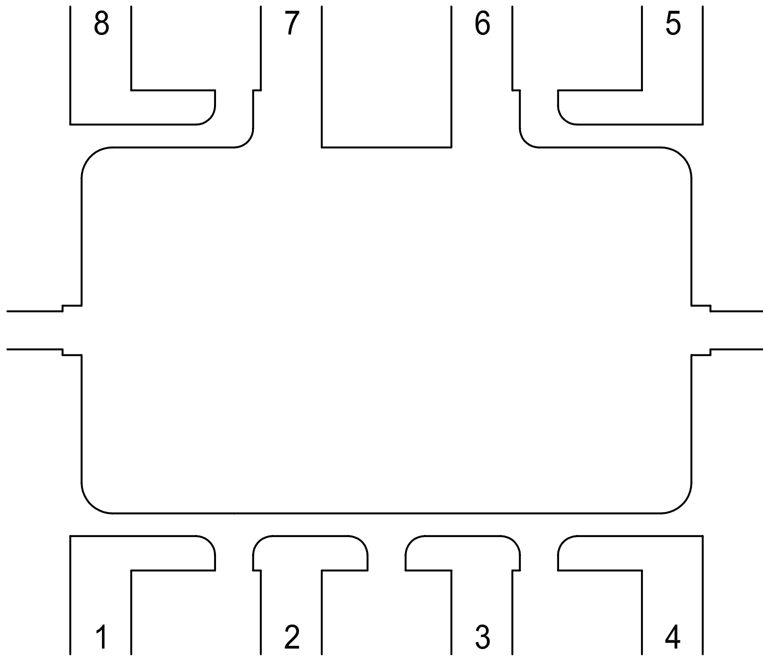
CIRTEK ELECTRONICS CORPORATION

116 East Avenue, Phase V, SEZ Laguna Technopark
Binan, Laguna, Philippines



Note: Fused pin 6 and 7 to pad.

PRODUCT INFORMATION

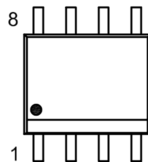
Customer :			
Device :		Device ID :	
Die Size :		Wafer Material :	
Package Type:	8L SOIC NB	No. of Wires :	

MATERIAL INFORMATION

Leadframe :	A194 with spot Ag	Pad Size :	96x160 mils
Epoxy :		Wire size :	
Molding Compound :		Lead Finish :	

MARKING INSTRUCTION

TOP :



BOTTOM : n/a

BONDING DIAGRAM NO.

REF. BONDING DIAGRAM NO.

SCALE: not to scale

DRAWN BY:

REVIEWED BY :

SPECIAL INSTRUCTIONS :

REVISION NO.			APPROVALS		
REV. #	DESCRIPTION	PCN #	DEPT	APPROVALS	DATE
			CUST		
			QSM		
			QC		
			MFG		